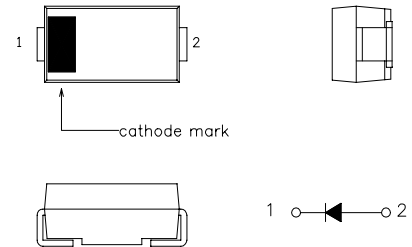


# DIODE Type : EC10DS2

## FEATURES

- \* Miniature Size, Surface Mount Device
- \* High Surge Capability
- \* Low Forward Voltage Drop
- \* Low Reverse Leakage Current
- \* Packaged in 12mm Tape and Reel
- \* Not Rolling During Assembly

## OUTLINE DRAWING



## Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC10DS2		Unit	
Repetitive Peak Reverse Voltage	$V_{RRM}$	200		V	
Non-repetitive Peak Reverse Voltage	$V_{RSM}$	400		V	
Average Rectified Output Current	$I_O$	0.74	Ta=25 °C *1	50Hz Half Sine Wave Resistive Load	A
		1.0	Ta=25 °C *2		
RMS Forward Current	$I_{F(RMS)}$	1.57		A	
Surge Forward Current	$I_{FSM}$	25	50Hz Half Sine Wave, 1cycle Non-repetitive	A	
Operating Junction Temperature Range	$T_{jw}$	-40 to +150		°C	
Storage Temperature Range	$T_{stg}$	-40 to +150		°C	

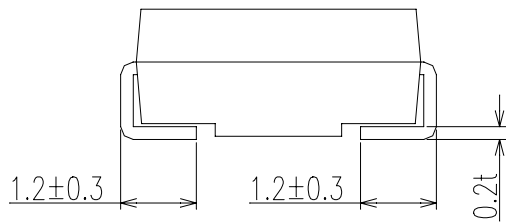
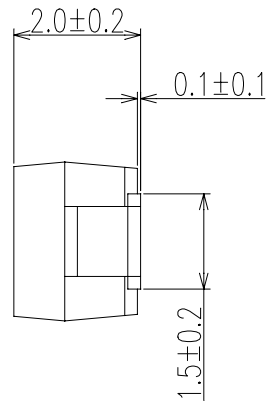
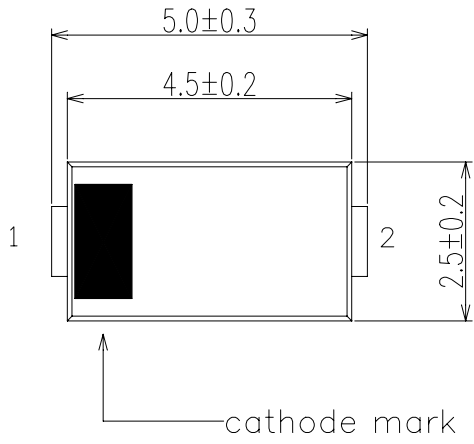
## Electrical • Thermal Characteristics

Characteristics	Symbol	Conditions	Min.	Typ.	Max.	Unit	
Peak Reverse Current	$I_{RM}$	$T_j = 25^\circ\text{C}$ , $V_{RM} = V_{RRM}$	-	-	10	$\mu\text{A}$	
Peak Forward Voltage	$V_{FM}$	$T_j = 25^\circ\text{C}$ , $I_{FM} = 1.0\text{A}$	-	-	1.1	V	
Thermal Resistance	$R_{th(j-a)}$	Junction to Ambient	*1	-	-	157	°C /W
			*2	-	-	108	

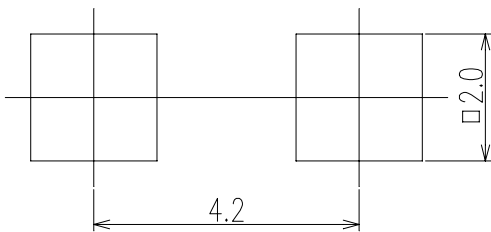
\*1 Glass Epoxy Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

\*2 Alumina Substrate Mounted (Soldering Lands=2x2mm, Both Sides)

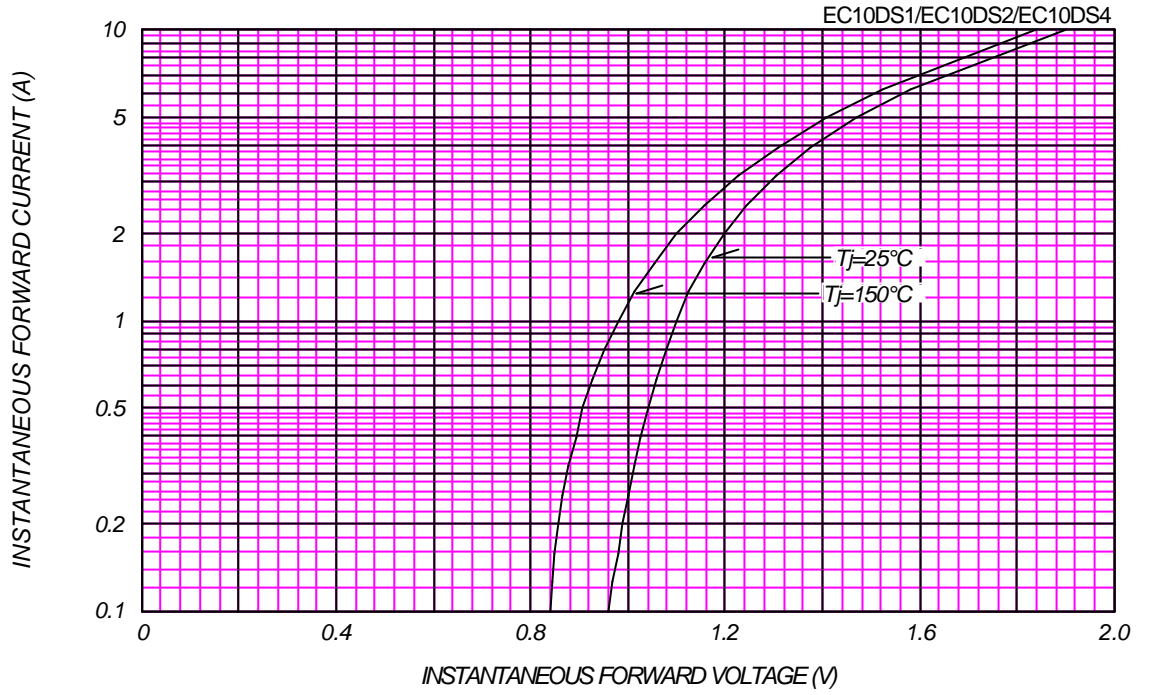
EC10D\*\_ OUTLINE DRAWING (Dimensions in mm)



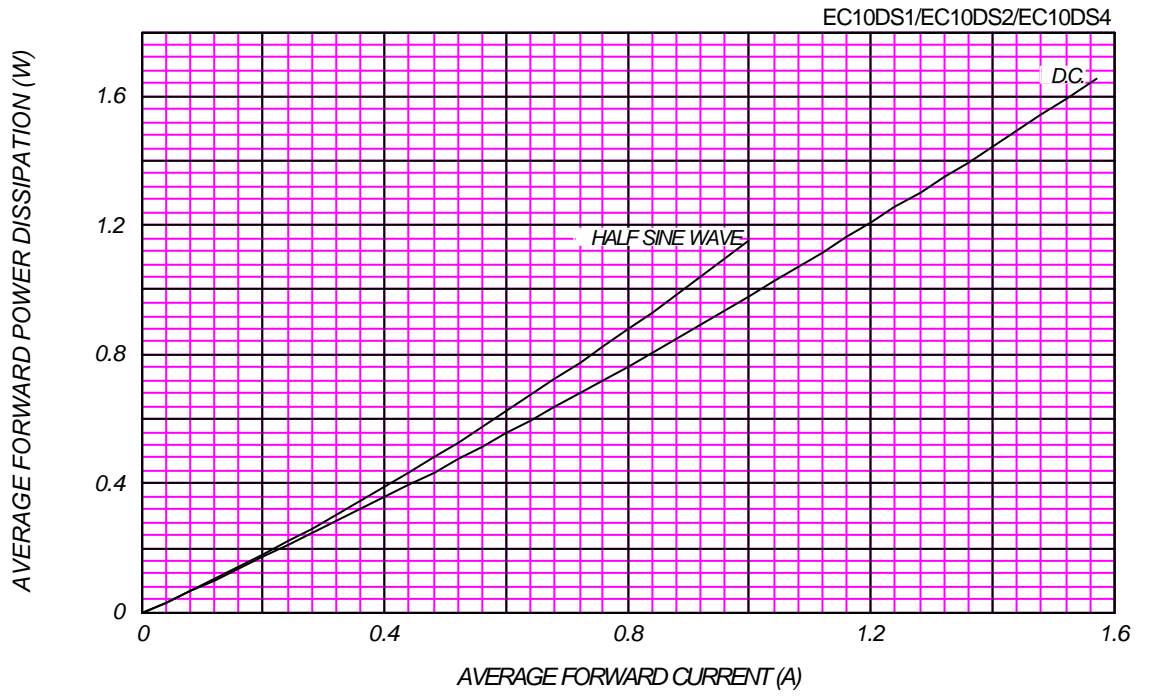
SOLDERING PAD



FORWARD CURRENT VS. VOLTAGE



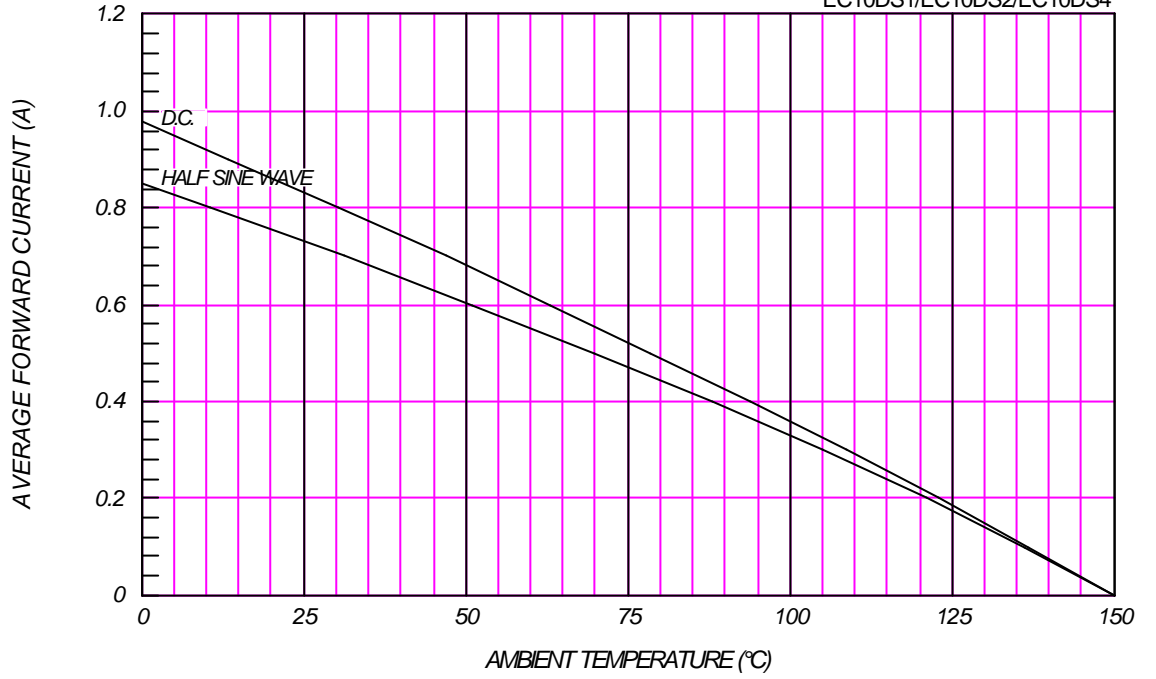
AVERAGE FORWARD POWER DISSIPATION



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Glass-Epoxy Substrate Mounted(Soldering Land=2x2mm)

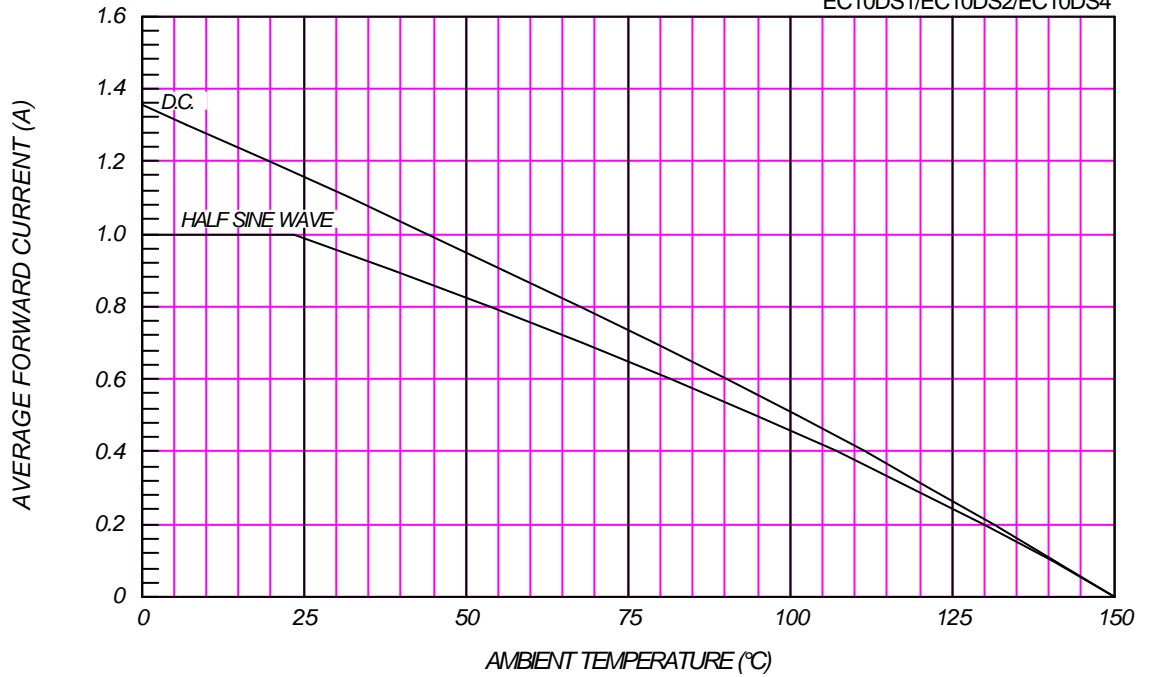
EC10DS1/EC10DS2/EC10DS4



AVERAGE FORWARD CURRENT VS. AMBIENT TEMPERATURE

Alumina Substrate Mounted(Soldering Land=2x2mm)

EC10DS1/EC10DS2/EC10DS4



### SURGE CURRENT RATINGS

f=50Hz, Half Sine Wave, Non-Repetitive, No Load

EC10DS1/EC10DS2/EC10DS4

